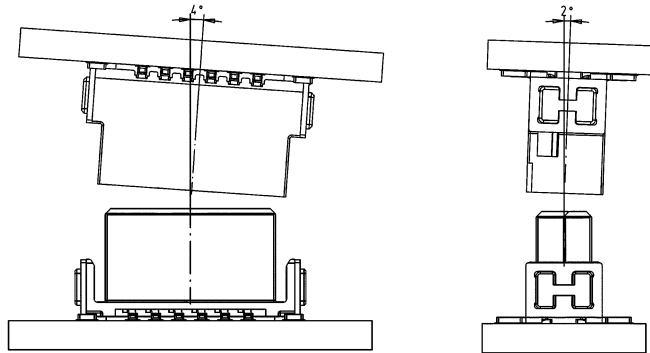
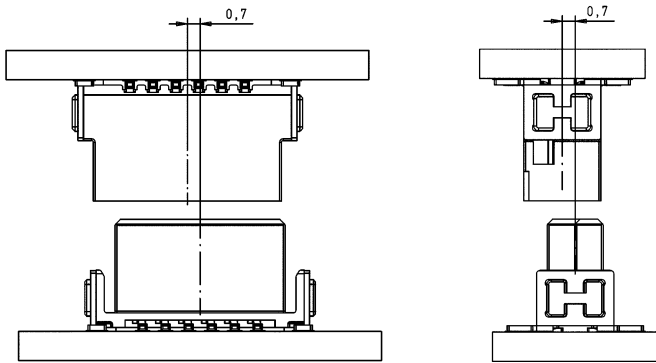


Mating conditions

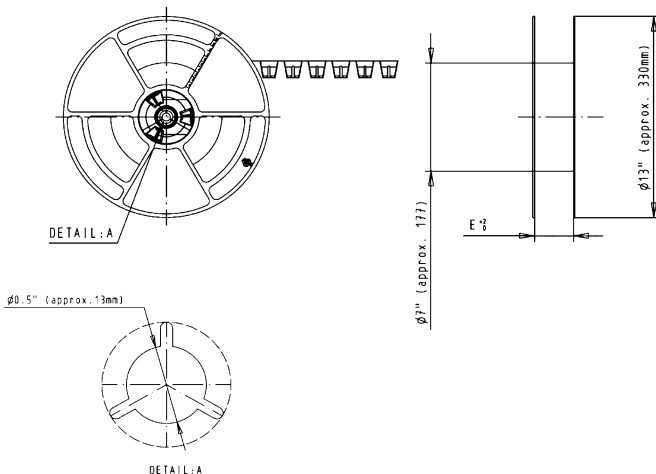
Inclination



Mismatching



Tape acc. to IEC 60286-3



Tape dimensions:	E
poles 6 to 12	24.4
poles 14 to 20	32.4
poles 22 to 40	44.4
poles 42 to 56	56.4
poles 58 to 80	72.4
poles 82 to 100	88.4

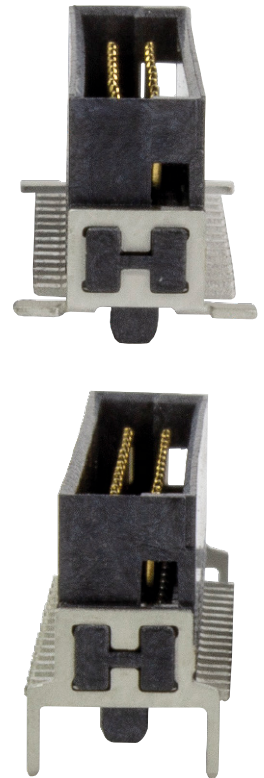
Processing notes

The har:flex® SMT/THR connectors meet the highest demands in terms of their processing capabilities.

The connectors are delivered in a tape and reel packaging optimized for automatic assembly machines. A vacuum cover enables the automatic assembly with a vacuum nozzle.

The insulation body material is high temperature resistant, and due to the black colour a secure camera recognition is ensured.

To ensure a reliable reflow soldering process, the signal pins are 100 % checked for coplanarity.



Process / Moisture Sensitivity

During the reflow solder process, the connector has to resist extreme variations in temperature. Connectors consist in general of both plastic and metal parts, which have a different behaviour during the solder process. The Process Sensivity and also the Moisture Sensivity are tested according the ECA/IPC/JEDEC J-STD-075 specification.

Process Sensivity:

PSL means Process Sensivity Level. PSL is a rating used to identify a component that is solder process sensitive. Damages of the connector after three times soldering are not permitted (e.g. melted edges).

Moisture Sensivity:

MSL means Moisture Sensivity Level. MSL is a rating indicating a component's susceptibility to damage due to absorbed moisture during storage. Damages of the connector after storage in damp heat and three times soldering are not permitted (e.g. blisters).

The har:flex® connectors are rated with **PSL R0** and **MSL 1**. This is the maximum possible rating in both categories. The har:flex® connector resists three times soldering at the following conditions without damages:

- min. 150 s beyond 217 °C (liquidus temperature, the melting point of the solder paste)
- min. 30 s beyond classification temperature (240 °C / 245 °C for har:flex®)
- Temperature solder profile according to ECA/IPC/JEDEC J-STD-075
- For MSL test, a storage of 168 hours at 85 °C and 85 % rel. humidity was carried out

As the result, the har:flex® connectors are not process sensitive and not moisture sensitive according to ECA/IPC/JEDEC J-STD-075.